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Description:

New Packages and Materials for Power Devices Market: By Package Type and Material (Chip-Scale Packaging, Wire Bonding Packaging, Silicon Carbide (SiC), Gallium Nitrid (GaN), Gallium Arsenide (GaAs) and Others), By End-Use (Automotive, Telecommunications and Computing, Electronics, Industrial and Others) and Region - Global Forecast Till 2023

Market Snapshot

The outlook towards power semiconductors remains positive. Over the years, tremendous development in packages and materials for power semiconductors has taken place. The global new packages and materials for power devices market is expected to witness a compound annual growth rate of 42.57% during the review period (2018-2023). Fueled by increasing application in computers and telecommunication, demand for power semiconductors is likely to remain substantially high throughout the projection period. Wide band gap (WBG) materials such as gallium nitride (GaN) and SiC are increasingly used in packaging materials given the growing need for higher power density.

Synopsis

This MRFR report offers a thorough assessment of the global new packages and materials for power devices market. It also includes five-year revenue analysis that ends at 2023. It also covers all the important market elements. Various growth drivers, opportunities and threats have discussed in the report. The scope of discussion also covers different types of packages and materials for power devices such as chip-scale packaging, wire bonding packaging, gallium nitrid (GaN), silicon carbide (SiC), gallium arsenide (GaAs) and Others. A revenue analysis based on end use of new packages and material for power devices is also available in the report.

Report Coverage

Historical market trends, market dynamics, forecast, market value by region as well as by segmentation, country-level analysis for each market segment, key player’s market share analysis and market factor analysis which covers supply chain and Porter’s five forces analysis of the market.

Companies Covered


Research Methodology

MRFR employs highly advanced research structure. Primary and secondary research techniques form the foundation of the research structure. Primary research inputs are mainly derived from interviews and interactions with key personnel. A bulk of secondary resources such as white papers, paid database, investor presentations, authenticated directories, etc. are utilized for affirmation of the gathered information. In addition, a multilayered evaluation process is used for confirming the accuracy of the data. Furthermore, top-down and bottom-up approaches are undertaking for ensuring zero discrepancy.

Other Description
For the scope of the research, MRFR’s report offers a comprehensive segmental analysis of the global market for new packages and materials for power devices

**By Package Type and Material**
- Chip-scale packaging
- Wire bonding packaging
- Silicon carbide (SiC)
- Gallium nitrid (GaN)
- Gallium arsenide (GaAs)
- Others (Hermetic packaging and Cu Clip packaging)

**By End-Use**
- Automotive
- Telecommunications and computing
  - Computing and telecommunication
  - Datacenters
  - Gaming systems
  - Cryptocurrency
- Electronics
- Industrial
- Others
  - Aerospace & defense
  - EV charging stations
  - Energy generation
  - Storage

**By Region**
- North America
- Europe
- Asia Pacific
- Rest of the World (RoW)
Global New Packages and Materials for Power Devices Market is expected to reach USD 2,567.2 Million.

**DRIVERS**
- Application in High Voltage and Medium Voltage Power Devices
- Need for Miniaturization in Semiconductor Devices
- Popularity of GaAs Photonics in the Electronics Sector
- Adoption of GaN-Based Power Devices in Industries such as Military and Aerospace

**KEY PLAYERS**
- NXP
- Mitsubishi Electric
- Infineon
- STI
- ON Semiconductor

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